

Thermally-Enhanced High Power RF GaN on SiC HEMT 1400 W, 50 V, DC - 1400 MHz

Description

The GTVA101K42EV is a 1400-watt GaN on SiC high electron mobility transistor (HEMT) for use in the DC to 1400 MHz frequency band. It is a input matched, high efficiency device in a thermally-enhanced package with bolt-down flange.



GTVA101K42EV Package H-36275-4

Features

- GaN on SiC HEMT technology
- Input matched
- Typical Pulsed CW performance, 960 1400 MHz, 50 V, single side, 128 µs pulse width, 10% duty cycle
 - Output power at P_{3dB} = 1400 W
 - Efficiency = 68%
 - Gain = 17 dB
- Pb-free and RoHS compliant

RF Characteristics¹

Pulsed CW Specifications (tested in Wolfspeed test fixture)

 V_{DD} = 50 V, I_{DO} = 75 mA, P_{OUT} (P3dB) = 1400 W peak, f = 1030 MHz, Pulse Width = 128 µs, Duty Cycle = 10%

Characteristic	Symbol	Min	Тур	Мах	Unit
Linear Gain	G _{ps}	17	19	_	dB
Return Loss	R	_	-19	-12	dB
Drain Efficiency	η_D	65	69	_	%
Output Mismatch Stress ²	VSWR	_	_	10:1	Ψ

Note ¹: All published data at $T_{CASE} = 25^{\circ}C$ unless otherwise indicated.

Note ²: No damage at all phase angles, V_{DD} = 50 V, I_{DQ} = 75mA, P_{OUT} = 1400 W Pulsed.

Note ³: ESD: Electrostatic discharge sensitive device—observe handling precautions!

DC Characteristics

Characteristic	Conditions	Symbol	Min	Тур	Мах	Unit
Drain-source Breakdown Voltage	V _{GS} = -8 V, I _D = 83.6 mA	V _{(BR)DSS}	125	_	_	V
Drain-source Leakage Current	$V_{GS} = -6 V, V_{DS} = 2 V$	I _{DSS}	62.7	75.5	—	А
Gate Threshold Voltage	V _{DS} = 10 V, I _D = 83.6 mA	V _{GS(th)}	-3.8	-3.0	-2.7	V

Recommended Operating Conditions

Parameter	Conditions	Symbol	Min	Тур	Мах	Unit
Drain Operating Voltage		V _{DD}	0	_	50	V
Gate Quiescent Voltage	V_{DS} = 50 V, I_{D} = 100 mA	V _{GS(Q)}	_	-3.1	_	V

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-source Voltage	V _{DSS}	150	V
Gate-source Voltage	V _{GS}	-10 to +2	V
Gate Current	I _G	167	mA
Drain Current	۱ _D	48	А
Junction Temperature	Tj	225	°C
Storage Temperature Range	T _{STG}	-65 to +150	°C

Operation above the maximum values listed here may cause permanent damage. Maximum ratings are absolute ratings; exceeding only one of these values may cause irreversible damage to the component. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. For reliable continuous operation, the device should be operated within the operating voltage range (V_{DD}) specified above.

Thermal Characteristics

Parameter	Symbol	Value	Units
Thermal Resistance, Junction to case ¹	R _{θJC}	.127	°C/W
Thermal Resistance, Junction to case ²	$R_{\theta JC}$.167	°C/W
Thermal Resistance, Junction to case ³	R _{θJC}	.166	°C/W

¹ Tcase = 85°C, P_{DISS} = 700 W, 100 µs Pulse Width, 10% Duty Cycle

² Tcase = 85°C, P_{DISS} = 700 W, 500 µs Pulse Width, 10% Duty Cycle ³ Tcase = 85°C, P_{DISS} = 700 W, Mode-S Signal

Electrical Characteristics When Tested in GTVA101K42EV-AMP2

Characteristics	Symbol	Min.	Тур.	Max.	Units	Conditions
RF Characteristics ¹ ($T_C = 25$ °C, F	₀ = 1.2 - 1.4	GHz unle	ss otherw	vise noted)	
Output Power ²	P _{OUT}	-	61	-	dBm	V_{DD} = 50 V, I_{DQ} = 1.8 A, P_{IN} = 44 dBm
Power Added Efficiency ²	η	-	55	-	%	V_{DD} = 50 V, I_{DQ} = 1.8 A, P_{IN} = 44 dBm
Gain ²	G	-	17	-	dB	V_{DD} = 50 V, I_{DQ} = 1.8 A, P_{IN} = 44 dBm

¹ Measured in the GTVA101K42EV-AMP2 Application Circuit

² Pulsed 500 μs, 10% Duty Cycle

Typical Performance of the GTVA101K42EV-AMP2

Test conditions unless otherwise noted: V_D = 50 V, I_{DQ} = 1800 mA, Pulse Width = 500 µs, Duty Cycle = 10%, Pin = 44 dBm, T_{BASE} = +25 °C



Figure 3. Power Added Eff. vs Frequency as a Function of Temperature







Figure 2. Output Power vs Frequency as a Function of Input Power



Figure 4. Power Added Eff. vs Frequency as a Function of Input Power







Drain Current (A)

Frequency (GHz)

Typical Performance of the GTVA101K42EV-AMP2

Test conditions unless otherwise noted: V_D = 50 V, I_{DO} = 1800 mA, Pulse Width = 500 µs, Duty Cycle = 10%, Pin = 44 dBm, T_{BASE} = +25 °C



Figure 9. Power Added Eff. vs Frequency as a Function of VD



Figure 11. Drain Current vs Frequency as a Function of VD



Figure 8. Output Power vs Frequency as a Function of IDQ



Figure 10. Power Added Eff. vs Frequency as a Function of IDQ



Figure 12. Drain Current vs Frequency as a Function of IDQ



Typical Performance of the GTVA101K42EV-AMP2

Test conditions unless otherwise noted: V_D = 50 V, I_{DQ} = 1800 mA, Pulse Width = 500 µs, Duty Cycle = 10%, Pin = 44 dBm, T_{BASE} = +25 °C



Figure 15. Large Signal Gain vs Input



Figure 17. Gate Current vs Input Power as a Function of Frequency



Figure 14. Power Added Eff. vs Input Power as a Function of Frequency 65 1.2 GHz 1.3 GHz 55 1.4 GHz Power Added Eff. (%) 45 35 25 15 5 24 29 34 39 44 Input Power (dBm)

Figure 16. Drain Current vs Input Power as a Function of Frequency



Figure 18. Output Power vs Input Power as a Function of Temperature



Power Added Eff. (%)

Typical Performance of the GTVA101K42EV-AMP2

Test conditions unless otherwise noted: V_D = 50 V, I_{DQ} = 1800 mA, Pulse Width = 500 µs, Duty Cycle = 10%, Pin = 44 dBm, T_{BASE} = +25 °C



Figure 21. Drain Current vs Input

Power as a Function of Temperature





Figure 20. Large Signal Gain vs Input



Figure 22. Gate Current vs Input Power as a Function of Temperature



Figure 24. Power Added Eff. vs Input Power as a Function of IDQ



Typical Performance of the GTVA101K42EV-AMP2

Test conditions unless otherwise noted: V_D = 50 V, I_{DQ} = 1800 mA, Pulse Width = 500 µs, Duty Cycle = 10%, Pin = 44 dBm, T_{BASE} = +25 °C



Figure 27. 2nd Harmonic vs Output Power as a Function of Frequency



Figure 29. 2nd Harmonic vs Output Power as a Function of IDQ



Figure 26. 3rd Harmonic vs Frequency as a Function of Temperature -25 85 °C 3rd Harmonic Level (dBc) 25 °C -40 °C -30 -35 -40 -45 1.20 1.25 1.30 1.35 1.40 Frequency (GHz)

Figure 28. 3rd Harmonic vs Output Power as a Function of Frequency







Typical Performance of the GTVA101K42EV-AMP2

Test conditions unless otherwise noted: V_D = 50 V, I_{DQ} = 1800 mA, Pin = -20 dBm, T_{BASE} = +25 °C



Figure 33. Input RL vs Frequency as a Function of Temperature









Figure 34. Input RL vs Frequency as a Function of Temperature



Figure 36. Output RL vs Frequency as a Function of Temperature



Typical Performance of the GTVA101K42EV-AMP2

Test conditions unless otherwise noted: V_D = 50 V, I_{DO} = 1800 mA, Pin = -20 dBm, T_{BASE} = +25 °C



Figure 39. Input RL vs Frequency as a Function Voltage



Figure 41. Output RL vs Frequency as a Function of Voltage



Frequency (GHz)



Figure 40. Input RL vs Frequency as a Function of IDQ



Figure 42. Output RL vs Frequency as a Function of Voltage



GTVA101K42EV-AMP2 Application Circuit Schematic



GTVA101K42EV-AMP2 Application Circuit



10

GTVA101K42EV-AMP2 Application Circuit Bill of Materials

Designator	Description	Qty
R1	RES, 30 OHMs, +/- 1%, 0805, 1/8W, YAGEO	1
R2, R3	RES, 10 OHMS, +/- 1%, 0805, 1/8W, YAGEO	2
R4, R5	RES, 1 OHMS, +/- 5%, 1206, 125mW, AVX	2
R6	RES, 10 OHMS, +/1%, 1206, 1/4W	1
C1	CAP, 47pF, +/- 5%, 250V, 0805, ATC 600F	1
C2,C4, C13, C15	CAP, 15uF, +/-20%, 10V, X7s, 1206, TDK	4
C3, C14, C19, C32, C36, C38, C40, C41	CAP, 56pF, +/- 5%, 250V, 0805, ATC, 600F	8
C5, C8, C9, C12	CAP, 2.2pF, +/1pF, 250V, 0805, ATC 600F	4
C6, C7, C10, C11	CAP, 7.5pF, +/25pF, 250V, 0805, ATC 600F	4
C16, C17, C34, C35	CAP, 470uF, +/-20%, 80V, Electrolytic, Vishay	4
C18, C33	CAP, 10uF, +/- 10%, 100V, X7S, 2220, TDK	2
C20, C22, C29, C31	CAP, 4.7pF, +/25pF, 250V, 0805, ATC 600F	4
C21, C24, C27, C30	CAP, .5pF, +/05pF, 250V, 0805, ATC 600F	4
C23, C28	CAP, 4.3pF, +/25pF, 250V, 0805, ATC 600F	2
C25, C26	CAP, 6.8pF, +/25pF, 250V, 0805, ATC 600F	2
C37, C39	CAP, 1uF, 100V, X7S, 0805, Murata	2
C44, C45, C46, C47	CAP, .01uF, 50V, X7R	4
C42, C43	CAP, 3.3pF, +/1pF, 250V, 0805, ATC 600F	2
W1, W2	Wire, 3.25", 18AWG	2
W3	Wire, 7", 12AWG	1
Q1	Transistor, GTVA101K42EV	1



Package Outline Specifications



Product Ordering Information

